



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-12
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FEJG*MV61BE6	A	Z8GA	2015-10-12
Amount	UoM	Unit type	ST ECOPACK Grade	
471.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	9.05 - 6.4 - 3.32	7	Through-hole	
Comment	Package: PDIP 7 - MDIP .25; MDF valid for VIPER16LN			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	FEIG*MV61BE6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
die (s)	Other inorganic materials	5.358	mg	supplier	die	Silicon (Si)	7440-21-3		5.278	mg	985069	11206	
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.01	mg	1866	21	
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.008	mg	1493	17	
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	373	4	
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.017	mg	3173	36	
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.006	mg	1120	13	
die (s)				supplier	passivation	Polyhydroxamide	55295-98-2		0.002	mg	373	4	
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	373	4	
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1120	13	
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.027	mg	5039	57	
Leadframe	Copper & its alloys	207.107	mg	supplier	alloy	Copper (Cu)	7440-50-8		201.072	mg	970860	426904	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		4.729	mg	22834	10040	
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.285	mg	1376	605	
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.248	mg	1197	527	
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.773	mg	3732	1641	
Die attach	Other inorganic materials	0.777	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.552	mg	710425	1172	
Die attach				supplier	glue or tape	epoxy resin	25068-38-6		0.117	mg	150579	248	
Die attach				supplier	glue or tape	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.062	mg	79794	132	
Die attach				supplier	glue or tape	Epoxy resin modifier	Proprietary		0.023	mg	29601	49	
Die attach				supplier	glue or tape	amine compound	Proprietary		0.023	mg	29601	49	
Bonding wire	Precious metals	0.169	mg	supplier	wire	Gold (Au)	7440-57-5		0.169	mg	1000000	359	
encapsulation	Other inorganic materials	252.23	mg	supplier	mold compound	Silica, vitreous	60676-86-0		219.44	mg	870000	465902	
encapsulation				supplier	mold compound	Epoxy resin	25068-38-6		25.223	mg	100000	53552	
encapsulation				supplier	mold compound	Phenol resin	29690-82-2		6.306	mg	25001	13389	
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		1.261	mg	4999	2677	
connections coating	Solder	5.359	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.359	mg	1000000	11378	